51C64HL
HIGH PERFORMANCE LOW POWER RIPPLEMODE™ 64K X1 CHMOS DYNAMIC RAM

	51C64HL-10	51C64HL-12
Maximum Access Time (ns)	100	120
Maximum Column Address Access Time (ns)	55	65
Maximum CHMOS Standby Current (mA)	0.05	0.05

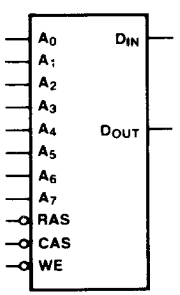
- **Ripplemode Operation**
  - Continuous data rate over 15 MHz
  - Random access within row
  - Flow through column latch for pipelining
  - t_{CAC} — 20, 25 ns
- **Low Input/Output Capacitance**
- **Fully TTL Compatible**
- **Low Power Data Retention**
  - Standby current, CHMOS — 50 μA (max.)
  - Refresh period, $\overline{RAS}$-Only — 64 ms (max.)
  - Data Retention Current — 80 μA (max.)
- **Low Operating Current — 37 mA (max.)**
- **High Reliability Plastic — 16 Pin DIP**

The Intel® 51C64HL is a high speed 65,536 x 1 dynamic Random Access Memory. Fabricated on Intel's CHMOS III-D technology, the 51C64HL offers features not provided by an NMOS dynamic RAM: Ripplemode for high data bandwidth, fast usable speed, and CHMOS standby current and extended $\overline{RAS}$-Only refresh for low data retention power. All inputs and outputs are TTL compatible and the input and output capacitances are significantly lowered to allow increased system performance.

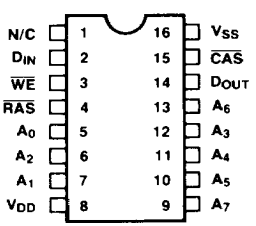
Ripplemode operation allows random or sequential access of up to 256 bits within a row, with cycle times as fast as 65 ns. Because of static column circuitry, the $\overline{CAS}$ clock is no longer in the critical timing path. The flow through column latch allows address pipelining while relaxing many critical system timing requirements for fast usable speed. These features make the 51C64HL ideally suited for cache based mainframe and mini computers, graphics, digital signal processing, and high performance microprocessor systems.

The 51C64HL offers a maximum standby current of 50 μA when $\overline{RAS} \geq V_{DD}$-0.5V. During standby (i.e. refresh only cycles), the refresh period can be extended to 64 ms to reduce the total current required for data retention to less than 80 μA (max). The 51C64HL combines low power with high density for portable and battery backup applications.

LOGIC SYMBOL



PIN CONFIGURATION



PIN NAMES

$\overline{RAS}$	ROW ADDRESS STROBE
$\overline{CAS}$	COLUMN ADDRESS STROBE
$\overline{WE}$	WRITE ENABLE
A_0-A_7	ADDRESS INPUTS
D_{IN}	DATA IN
D_{OUT}	DATA OUT
V_{DD}	POWER (+5V)
V_{SS}	GROUND

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Order Number: 280026-001

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ABSOLUTE MAXIMUM RATINGS†

Ambient Temperature Under
Bias . . . . . -10°C to +80°C
Storage Temperature . . . Plastic -55°C to +125°C
Voltage on Any Pin except V_{DD} and D_{OUT}
Relative to V_{SS} . . . . . -2.0V to 7.5V
Voltage on V_{DD} Relative to V_{SS} . . . . . -1.0V to 7.5V
Voltage on D_{OUT}
Relative to V_{SS} . . . . . -2.0 to V_{DD} + 1V
Data Out Current . . . . . 50 mA
Power Dissipation . . . . . 1.0 W

†COMMENT
Stresses above those listed under "Absolute Maximum Rating" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

D.C. CHARACTERISTICS[1]

$t_A = 0°C$ to $70°C$, $V_{DD} = 5V \pm 10\%$, $V_{SS} = 0V$, unless otherwise noted.

Symbol	Parameter	51C64HL			Unit	Test Conditions	Notes
		Min.	Typ.[2]	Max.			
I_{DD1}	V_{DD} Supply Current, Operating		27	37	mA	$t_{RC} = t_{RC}$ (min), for −10 A.C. spec	3,4
			23	35	mA	$t_{RC} = t_{RC}$ (min), for −12 A.C. spec.	
I_{DD2}	V_{DD} Supply Current, TTL Standby		0.7	2	mA	$\overline{RAS}$ and $\overline{CAS}$ at V_{IH}, all other inputs and output ≥ V_{SS}	
I_{DD3}	V_{DD} Supply Current, $\overline{RAS}$-Only Cycle		24	37	mA	$t_{RC} = t_{RC}$ (min), for −10 A.C. spec	4
			20	35	mA	$t_{RC} = t_{RC}$ (min), for −12 A.C. spec	
I_{DD4}	V_{DD} Supply Current, Ripplemode™		18	37	mA	$t_{PC} = t_{PC}$ (min), for −10 A.C. spec	3,4
			17	35	mA	$t_{PC} = t_{PC}$ (min), for −12 A.C. spec	
I_{DD5}	V_{DD} Supply Current, Standby, Output Enabled		3	4	mA	$\overline{RAS}$ at V_{IH}, $\overline{CAS}$ at V_{IL}, all other inputs and output ≥ V_{SS}	3
I_{DD6}	V_{DD} Supply Current, CHMOS Standby		0.008	0.05	mA	$\overline{RAS} \geq V_{DD} - 0.5V$ and $\overline{CAS}$ at V_{IH}, all other inputs and output ≥ V_{SS}	
$\|I_{LI}\|$	Input Load Current (any pin)			1	μA	$V_{IN} = V_{SS}$ to V_{DD}	
$\|I_{LO}\|$	Output Leakage Current for High Impedance State			1	μA	$\overline{RAS}$ and $\overline{CAS}$ at V_{IH}, $D_{OUT} = V_{SS}$ to V_{DD}	
V_{IL}	Input Low Voltage (all inputs)	−1.0		0.8	V		5
V_{IH}	Input High Voltage (all inputs)	2.4		$V_{DD}+1$	V		5
V_{OL}	Output Low Voltage			0.4	V	$I_{OL} = 4.2$ mA	6
V_{OH}	Output High Voltage	2.4			V	$I_{OH} = -5$ mA	6

NOTES:
1. All voltages referenced to V_{SS}.
2. Typical values are at $T_A = 25°C$ and $V_{DD} = +5V$.
3. I_{DD} is dependent on output loading when the device output is selected. Specified I_{DD} (max) is measured with the output open.
4. I_{DD} is dependent upon the number of address transitions while $\overline{CAS}$ is at V_{IH}. Specified I_{DD} (max) is measured with a maximum of two transitions per address input per random cycle, one transition per access cycle in Ripplemode.
5. Specified V_{IL} (min) is steady state operation. All A.C. parameters are measured with V_{IL} (min) ≥ V_{SS} and V_{IH} (max) ≤ V_{DD}.
6. Test conditions apply only for D.C. Characteristics. All A.C. parameters are measured with a load equivalent to two TTL loads and 50 pF.

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CAPACITANCE†

$T_A = 25°C$, $V_{DD} = 5V \pm 10\%$, $V_{SS} = 0V$, unless otherwise noted.

†NOTE:
Capacitance is measured at worst case voltage levels with a programmable capacitance meter.

Symbol	Parameter	Typ.	Max	Unit
C_{IN1}	Address, D_{IN}	3	4	pF
C_{IN2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$	4	5	pF
C_{OUT}	D_{OUT}	4	6	pF

A.C. CHARACTERISTICS [1, 2, 3]

$T_A = 0°C$ to $70°C$, $V_{DD} = 5V \pm 10\%$, $V_{SS} = 0V$, unless otherwise noted.

Read, Write, Read-Modify-Write and Refresh Cycles

#	JEDEC Symbol	Symbol	Parameter	51C64HL-10		51C64HL-12		Unit	Notes
				Min.	Max.	Min.	Max.		
1	t_{RL1RH1}	t_{RAS}	$\overline{RAS}$ Pulse Width	100	75000	120	75000	ns	
2	t_{RL2RL2}	t_{RC}	Random Read or Write Cycle Time	160		190		ns	
3	t_{RH2RL2}	t_{RP}	$\overline{RAS}$ Precharge Time	50		60		ns	
4	t_{RL1CH1}	t_{CSH}	$\overline{CAS}$ Hold Time	100		120		ns	
5	t_{AVRL2}	t_{ASR}	Row Address Set-up Time	0		0		ns	
6	t_{RL1AX}	t_{RAH}	Row Address Hold Time	15		15		ns	
7	t_{CH2CL2}	t_{CP}	$\overline{CAS}$ Precharge Time	10		15		ns	
8	t_{CH2RL2}	t_{CRP}	$\overline{CAS}$ to $\overline{RAS}$ Precharge Time	−20		−20		ns	
9	t_{RL1CL2}	t_{RCD}	$\overline{RAS}$ to $\overline{CAS}$ Delay	30	80	35	95	ns	4
10	t_{AVCL2}	t_{ASC}	Column Address Set-up Time	0		0		ns	
11	t_{CL1AX}	t_{CAH}	Column Address Hold Time	10		15		ns	
12	t_{RL1AX}	t_{AR}	Column Address Hold Time From $\overline{RAS}$	40		50		ns	
	t_{RVRV}	$t_{REF\,1}$	Time Between Refresh		4		4	ms	5
	t_{RVRV}	$t_{REF\,2}$	Time Between Refresh ($\overline{RAS}$-Only)		64		64	ms	5
	t_T	t_T	Transition Time (Rise and Fall)	3	50	3	50	ns	6
13	t_{CL1QX}	t_{ON}	Output Buffer Turn On Delay	0	20	0	25	ns	
14	t_{CH2QZ}	t_{OFF}	Output Buffer Turn Off Delay	0	20	0	25	ns	

NOTES:
1. All voltages referenced to V_{SS}.
2. An initial pause of 100 microseconds is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing a $\overline{RAS}$ clock such as $\overline{RAS}$-Only refresh). Eight initialization cycles are required after extended periods of bias without clocks (greater than 64 ms).
3. A.C. Characteristics assume $t_T = 5$ ns. All A.C. parameters are measured with a load equivalent to two TTL loads and 50 pF, V_{IL} (min) $\geq V_{SS}$ and V_{IH} (max) $\leq V_{DD}$.
4. t_{RCD} (max) is specified for reference only.
5. The 51C64HL extends the refresh period to 64 ms during $\overline{RAS}$-Only refresh operation.
6. t_T is measured between V_{IH} (min) and V_{IL} (max).

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A.C. CHARACTERISTICS (Con't.)

Read Cycle

#	JEDEC Symbol	Symbol	Parameter	51C64HL-10		51C64HL-12		Unit	Notes
				Min.	Max.	Min.	Max.		
15	t_{RL1QV}	t_{RAC}	Access Time From $\overline{RAS}$		100		120	ns	7
16	t_{CL1QV}	t_{CAC}	Access Time From $\overline{CAS}$		20		25	ns	8,9
17	t_{AVQV}	t_{CAA}	Access Time From Column Address		55		65	ns	9,10
18	$t_{CL1CH1(R)}$	$t_{CAS(R)}$	$\overline{CAS}$ Pulse Width (Read Cycle)	20	75000	25	75000	ns	
19	$t_{CL1RH1(R)}$	$t_{RSH(R)}$	$\overline{RAS}$ Hold Time (Read Cycle)	10		10		ns	
20	t_{WH2CL2}	t_{RCS}	Read Command Set-up Time	0		0		ns	
21	t_{AVRH1}	t_{CAR}	Column Address to $\overline{RAS}$ Set-up Time	55		65		ns	
22	t_{CH2WX}	t_{RCH}	Read Com. Hold Time Ref. to $\overline{CAS}$	0		0		ns	11
23	t_{RH2WX}	t_{RRH}	Read Com. Hold Time Ref. to $\overline{RAS}$	10		10		ns	11

Write Cycle

#	JEDEC Symbol	Symbol	Parameter	51C64HL-10		51C64HL-12		Unit	Notes
				Min.	Max.	Min.	Max.		
24	$t_{CL1RH1(W)}$	$t_{RSH(W)}$	$\overline{RAS}$ Hold Time (Write Cycle)	35		40		ns	
25	$t_{CL1CH1(W)}$	$t_{CAS(W)}$	$\overline{CAS}$ Pulse Width (Write Cycle)	30	75000	35	75000	ns	
26	t_{WL1RH1}	t_{RWL}	Write Command to $\overline{RAS}$ Lead Time	30		35		ns	
27	t_{WL1CH1}	t_{CWL}	Write Command to $\overline{CAS}$ Lead Time	30		35		ns	
28	t_{WL1WH1}	t_{WP}	Write Command Pulse Width	20		25		ns	
29	t_{WL1CL2}	t_{WCS}	Write Command Set-up Time	0		0		ns	12
30	t_{CL1WH1}	t_{WCH}	Write Command Hold Time	30		35		ns	
31	t_{DVCL2}	t_{DS}	Data-In Set-up Time	0		0		ns	
32	t_{CL1DX}	t_{DH}	Data-In Hold Time	20		25		ns	

NOTES:

7. Assumes that $t_{RCD} \leq t_{RCD}$ (max). If $t_{RCD} > t_{RCD}$ (max) then t_{RAC} will increase by the amount that t_{RCD} (max).
8. Assumes $t_{RCD} \geq t_{RCD}$ (max).
9. If $t_{ASC} < (t_{CAA}$ (max) - t_{CAC} (max) - $t_T)$, then access time is defined by t_{CAA} rather than by t_{CAC}.
10. When a Ripplemode read cycle immediately follows a Ripplemode write cycle, the specification must be increased by 10 ns.
11. Either t_{RCH} or t_{RRH} must be satisfied.
12. t_{WCS}, t_{RWD}, t_{CWD} and t_{AWD} are specified as reference points only. If $t_{WCS} \geq t_{WCS}$ (min), the cycle is a $\overline{CAS}$ controlled write cycle (early write cycle) and the data out pin will remain in high impedance throughout the entire cycle. If $t_{CWD} \geq t_{CWD}$ (min) and $t_{RWD} \geq t_{RWD}$ (min) and $t_{AWD} \geq t_{AWD}$ (min), then the cycle is a read-modify-write cycle and the data out will contain the data read from the selected address. If any of the above conditions are not satisfied, the condition of the data out is indeterminate.

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A.C. CHARACTERISTICS (Con't.)

Read-Modify-Write Cycle 13

#	JEDEC Symbol	Symbol	Parameter	51C64HL-10		51C64HL-12		Unit	Notes
				Min.	Max.	Min.	Max.		
33	$t_{RL2RL2(RMW)}$	t_{RWC}	Read-Modify-Write (RMW) Cycle Time	195		230		ns	
34	$t_{RL1RH1(RMW)}$	t_{RRW}	RMW Cycle $\overline{RAS}$ Pulse Width	135	75000	160	75000	ns	
35	$t_{CL1CH1(RMW)}$	t_{CRW}	RMW Cycle $\overline{CAS}$ Pulse Width	55	75000	65	75000	ns	
36	t_{RL1WL2}	t_{RWD}	$\overline{RAS}$ to $\overline{WE}$ Delay	100		120		ns	14
37	t_{CL1WL2}	t_{CWD}	$\overline{CAS}$ to $\overline{WE}$ Delay	20		25		ns	14
38	t_{AVWL2}	t_{AWD}	Column Address to $\overline{WE}$ Delay	55		65		ns	14

Ripplemode Cycle 15

#	JEDEC Symbol	Symbol	Parameter	51C64HL-10		51C64HL-12		Unit	Notes
				Min.	Max.	Min.	Max.		
39	t_{CH2QV}	t_{CAP}	Access Time From Column Precharge		60		70	ns	16,17
40	$t_{CL2CL2(R)}$	t_{PC}	Ripplemode Read or Write Cycle	65		75		ns	16,17
41	$t_{CL2CL2(RRMW)}$	t_{PCM}	Ripplemode RMW Cycle Time	95		110		ns	

NOTES:

13. The parameters shown in the Read-Modify-Write timing diagrams which are not listed in the table are previously specified.
14. t_{WCS}, t_{RWD}, t_{CWD} and t_{AWD} are specified as reference points only. If $t_{WCS} \geq t_{WCS}$ (min), the cycle is a $\overline{CAS}$ controlled write cycle (early write cycle) and the data out pin will remain in high impedance throughout the entire cycle. If $t_{CWD} \geq t_{CWD}$ (min) and $t_{RWD} \geq t_{RWD}$ (min) and $t_{AWD} \geq t_{AWD}$ (min), then the cycle is a read-modify-write cycle and the data out will contain the data read from the selected address. If any of the above conditions are not satisfied, the condition of data out is indeterminate.
15. All previously specified A.C. Characteristics are applicable.
16. Access time is determined by the longer of t_{CAA} or t_{CAC} or t_{CAP}.
17. When a Ripplemode read cycle immediately follows a Ripplemode write cycle, the specification must be increased by 10 ns.

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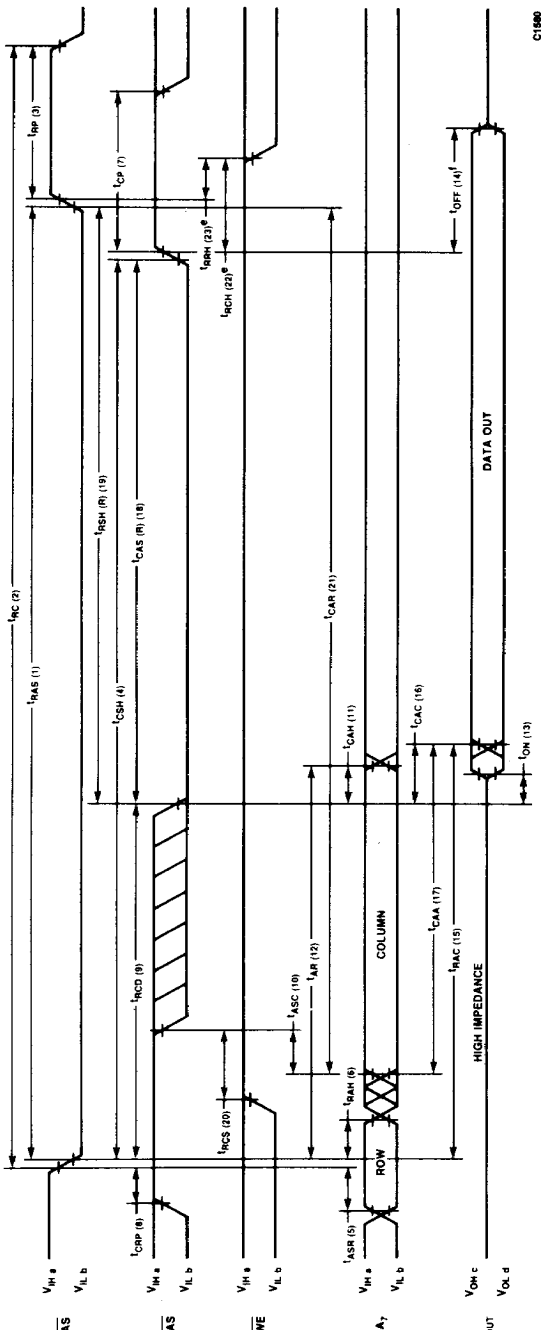
WAVEFORMS
Read Cycle



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. Either t_{RCH} or t_{RRH} must be satisfied.
f. t_{OFF} is measured to $|I_{OUT}| \leq |I_{LO}|$.

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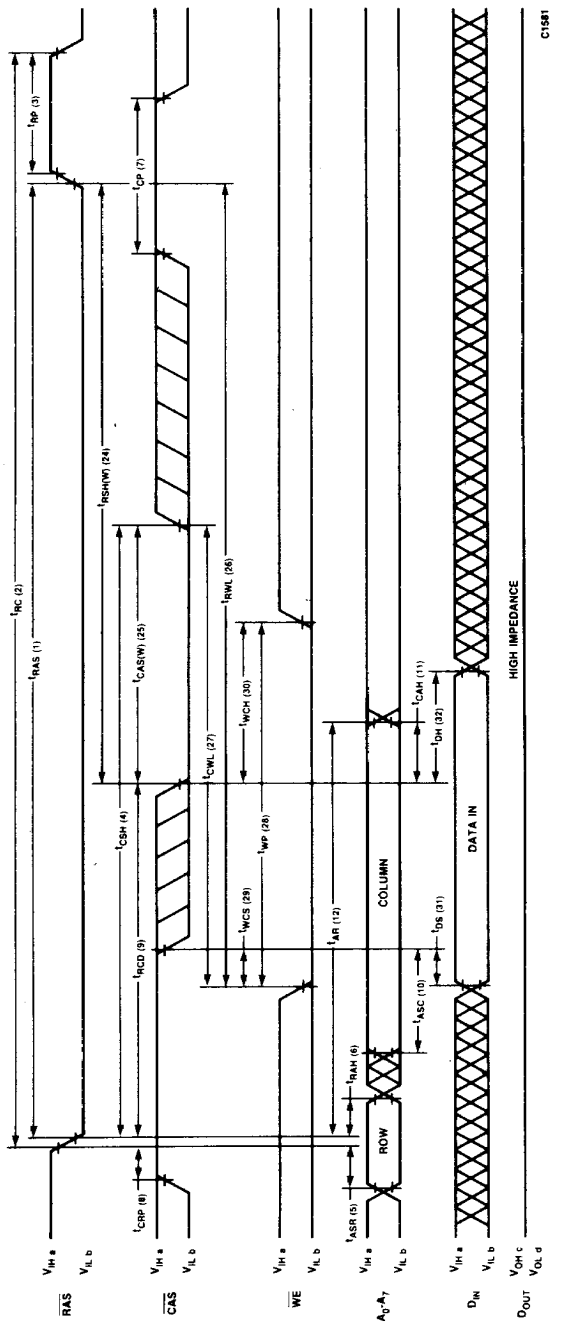
WAVEFORMS (Cont.)
Write Cycle ($\overline{CAS}$ Controlled)[e]



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. $\overline{WE}$ is low prior to or simultaneously with $\overline{CAS}$ low transition. $\overline{CAS}$ latches column address and data-in.

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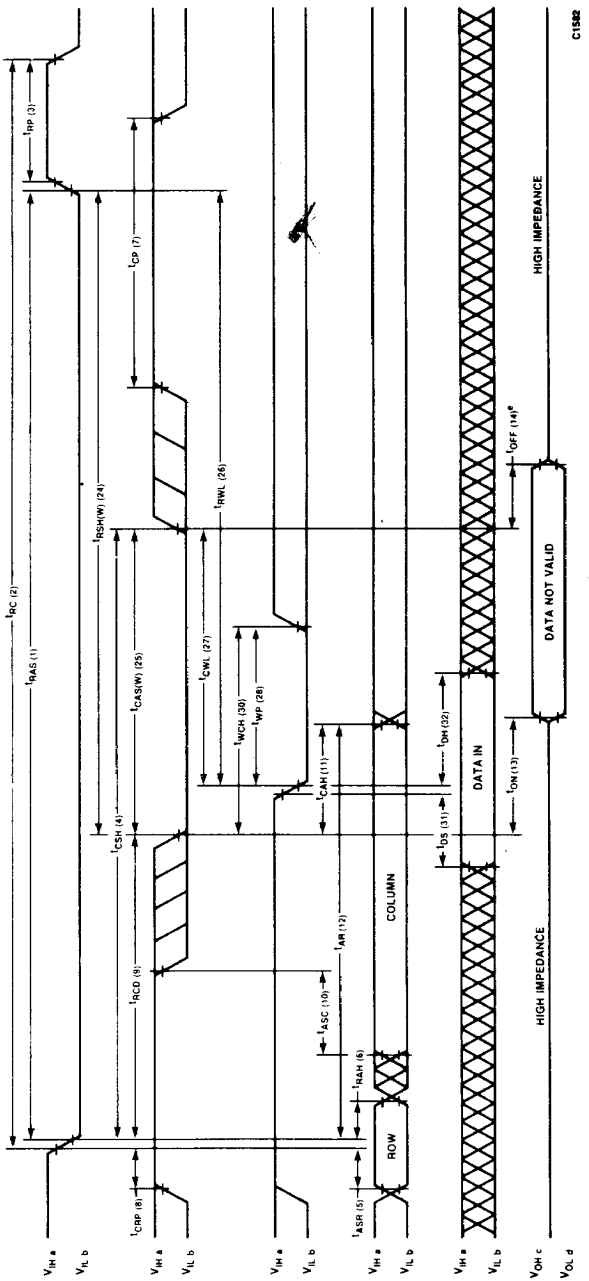
WAVEFORMS (Cont.)
Write Cycle ($\overline{WE}$ Controlled)[f]



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. t_{OFF} is measured to $|I_{OUT}| \leq |I_{LO}|$.
f. $\overline{CAS}$ is low prior to the $\overline{WE}$ low transition. $\overline{CAS}$ latches the column address while $\overline{WE}$ latches the data-in.

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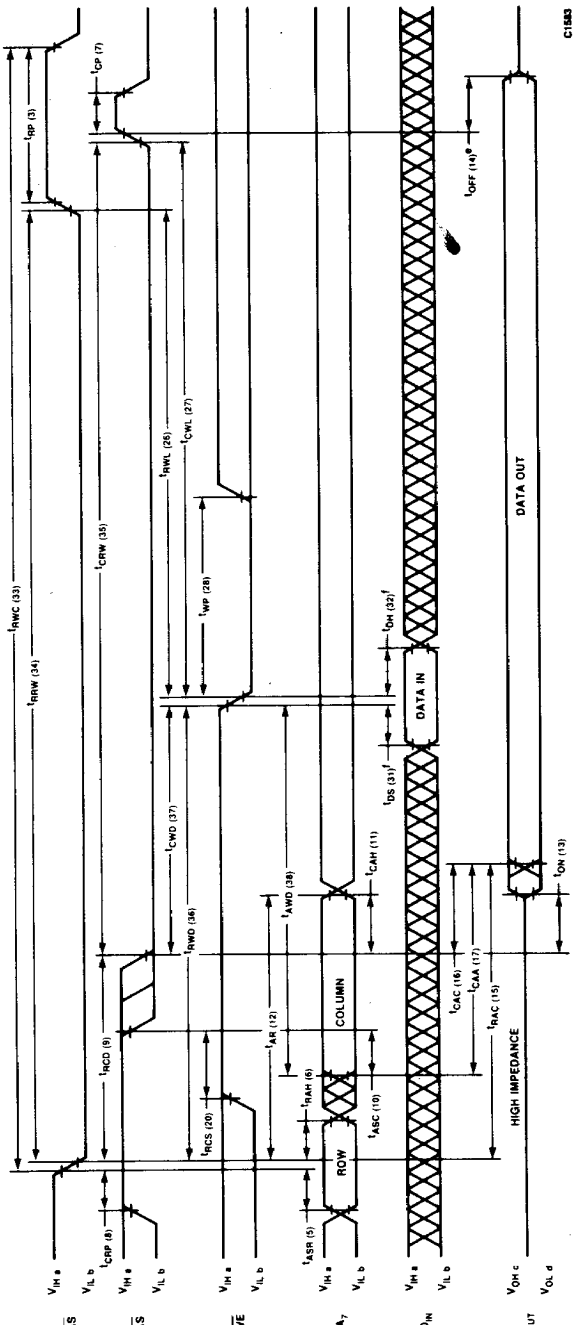
WAVEFORMS (Cont.)
Read/Modify/Write Cycle



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. t_{OFF} is measured to $I_{OUT} \leq |I_{LO}|$.
f. t_{DS} and t_{DH} are referenced to $\overline{CAS}$ or $\overline{WE}$, whichever occurs last.

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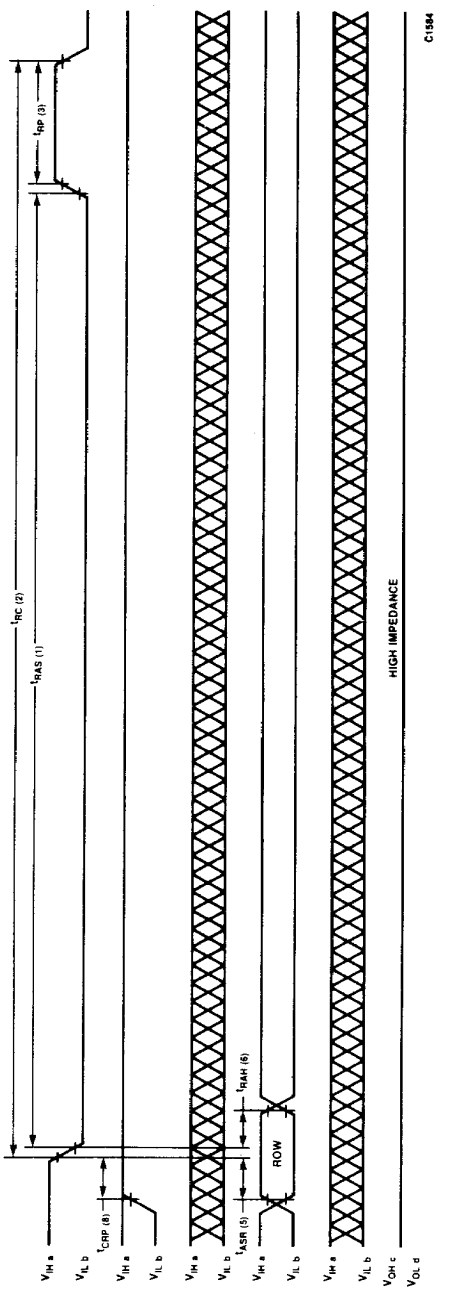
WAVEFORMS (Cont.)
RAS-Only Refresh Cycle



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.

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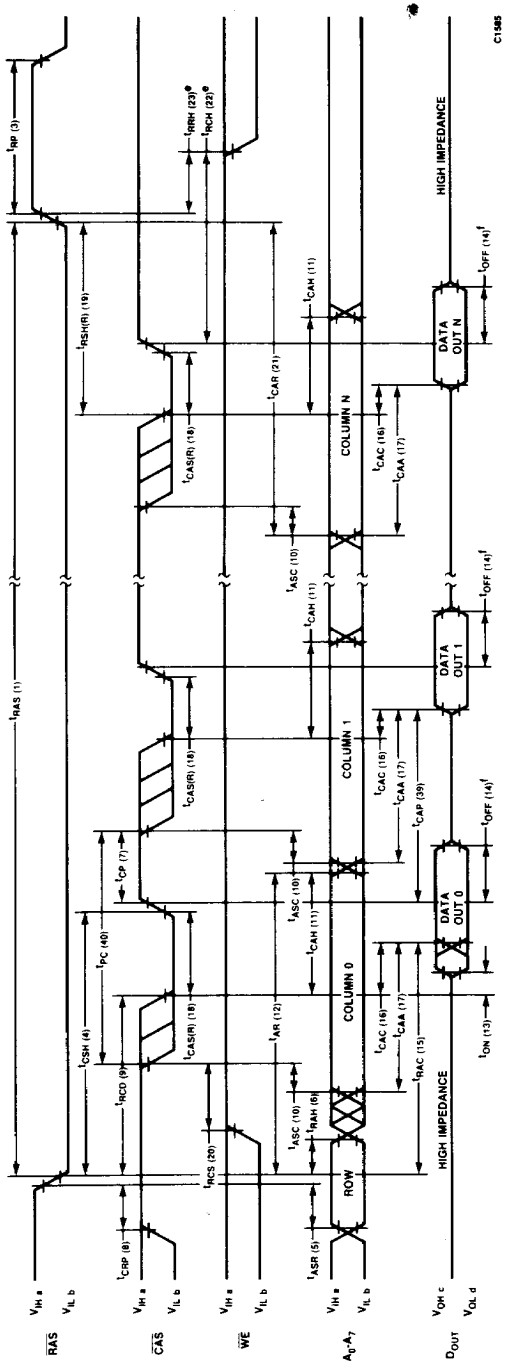
WAVEFORMS (Cont.)
Ripplemode Read Cycle



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. Either t_{RCH} or t_{RPH} must be satisfied.
f. t_{OFF} is measured to $I_{OUT} \leq |I_{LO}|$.

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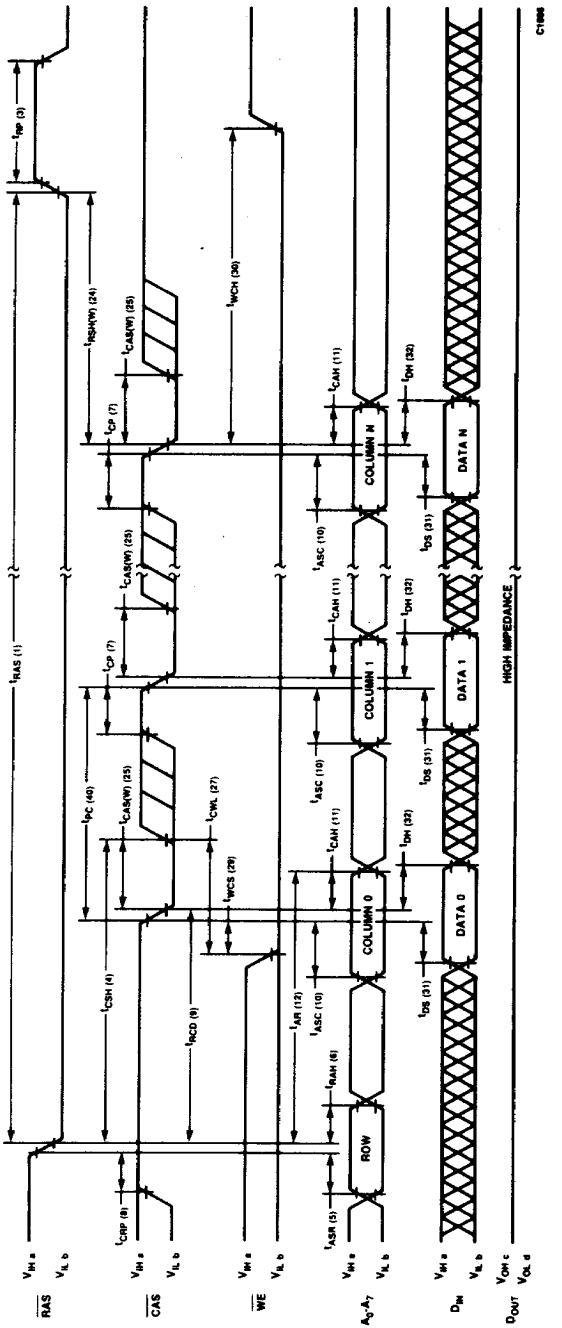
WAVEFORMS (Cont.)
Ripplemode Write Cycle ($\overline{CAS}$ Controlled)[e]



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. $\overline{WE}$ is low prior to or simultaneously with $\overline{CAS}$ low transition. $\overline{CAS}$ latches column address and data-in.

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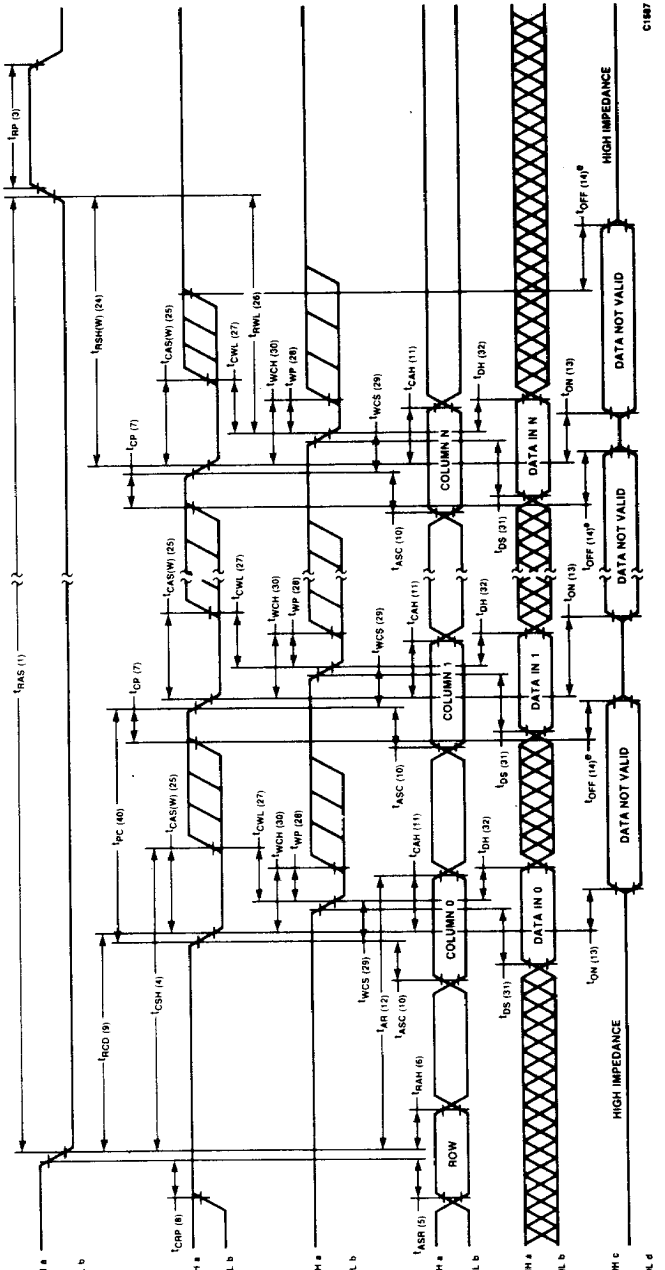
WAVEFORMS (Cont.)
Ripplemode Write Cycle ($\overline{WE}$ Controlled)[f]



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. t_{OFF} is measured to $|I_{OUT}| \leq |I_{LO}|$.
f. $\overline{CAS}$ is low prior to the $\overline{WE}$ low transition. $\overline{CAS}$ latches the column address while $\overline{WE}$ latches the data-in.

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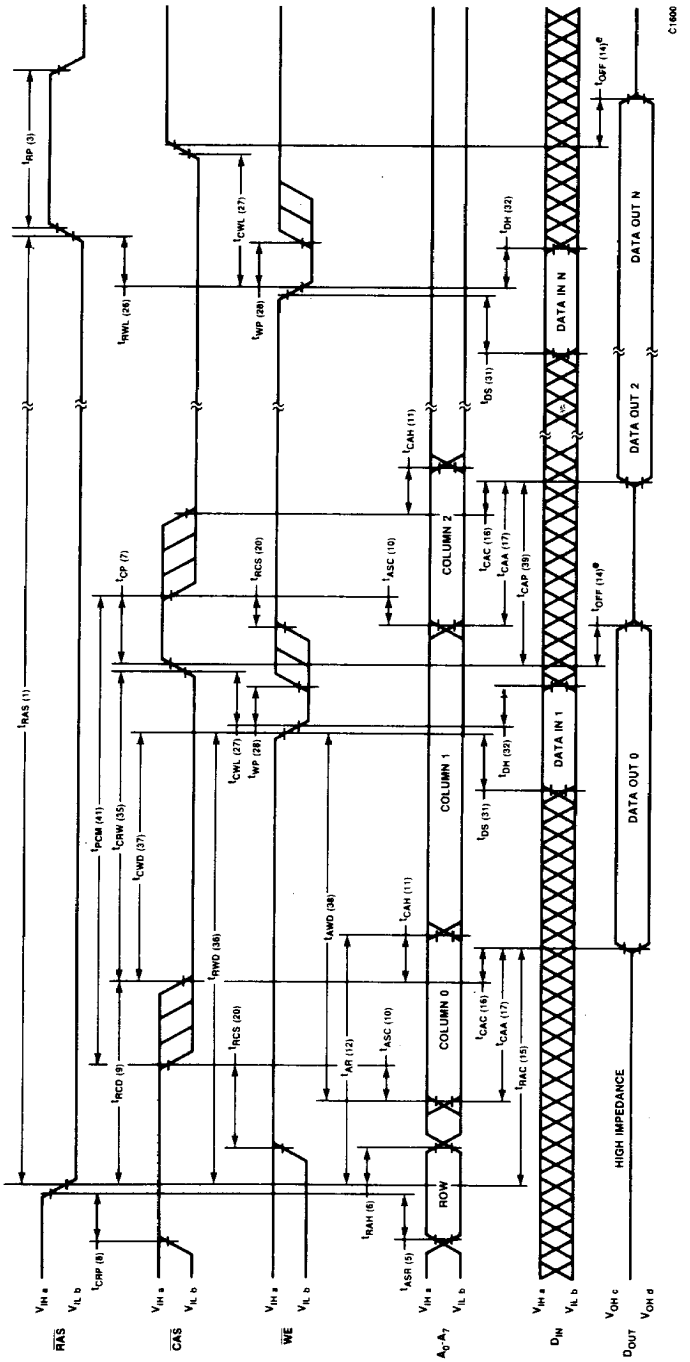
WAVEFORMS
Ripplemode Read/Modify/Write Cycle[f]



NOTES:
a.,b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c.,d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. t_{OFF} is measured to $|I_{OUT}| \leq |I_{LO}|$.
f. $\overline{CAS}$ is low prior to $\overline{WE}$ low transition. $\overline{CAS}$ latches the column addresses while $\overline{WE}$ latches data-in.

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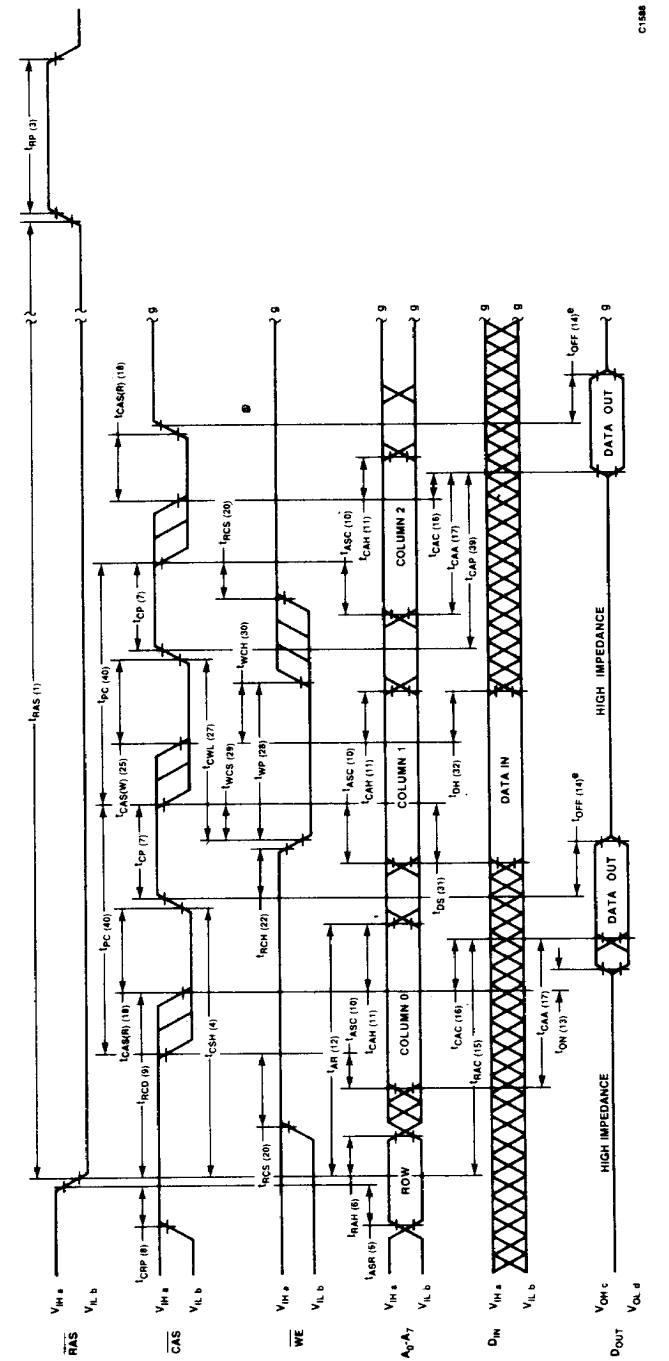
WAVEFORMS
Ripplemode Read/Write/Read. . . Cycle ($\overline{CAS}$ Controlled)[f]



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. t_{OFF} is measured to $|I_{OUT}| \leq |I_{LO}|$.
f. $\overline{WE}$ is low prior to $\overline{CAS}$ low transition. $\overline{CAS}$ latches column addresses and data-in.
g. The cycle can be terminated either by a read or a write operation followed by a $\overline{RAS}$ high transition. See page 11 or 12 for timings.

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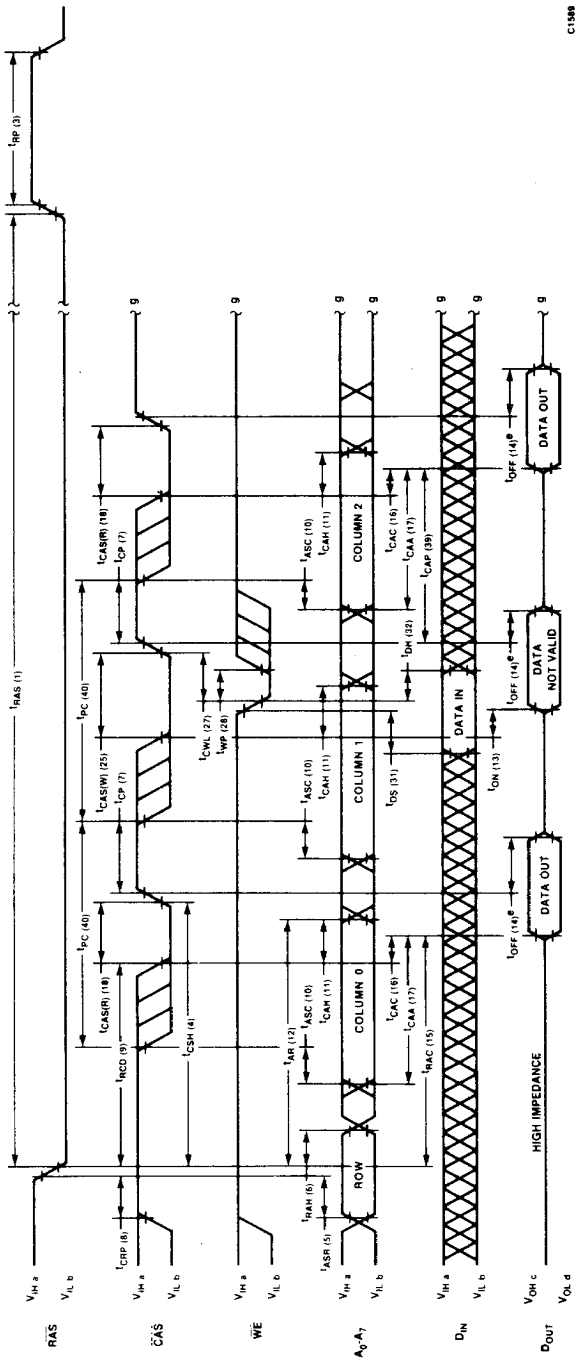
WAVEFORMS
Ripplemode Read/Write/Read. . . Cycle ($\overline{WE}$ Controlled)[f]



NOTES:
a., b. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals.
c., d. V_{OH} (min) and V_{OL} (max) are reference levels for measuring timing of D_{OUT}.
e. t_{OFF} is measured to $|I_{OUT}| \leq |I_{LO}|$.
f. $\overline{CAS}$ is low prior to $\overline{WE}$ low transition. $\overline{CAS}$ latches the column addresses while $\overline{WE}$ latches data-in.
g. The cycle can be terminated either by a read or a write operation followed by a $\overline{RAS}$ high transition. See page 11 or 13 for timings.

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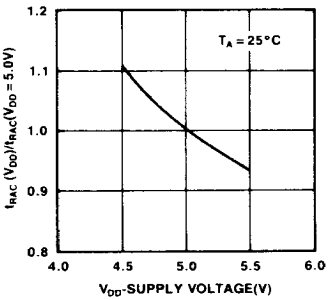
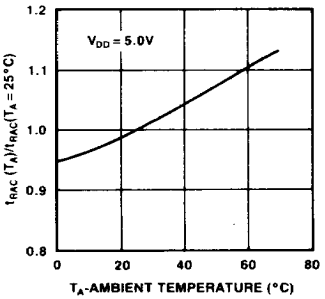
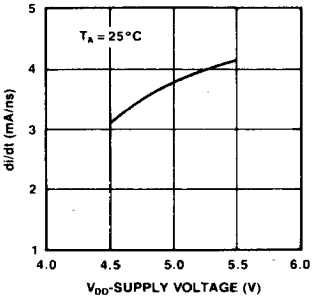
GRAPH 1
TYPICAL ACCESS TIME
t_{RAC} (NORMALIZED) vs. V_{DD}



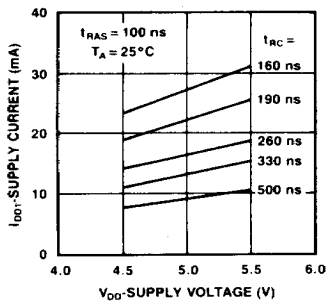
GRAPH 2
TYPICAL ACCESS TIME
t_{RAC}(NORMALIZED) vs. T_A



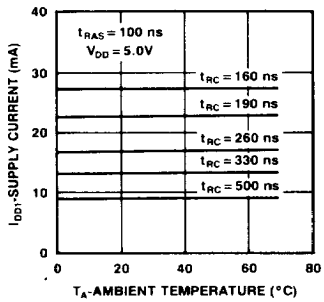
GRAPH 3
TYPICAL CURRENT TRANSIENTS
di/dt vs. V_{DD}



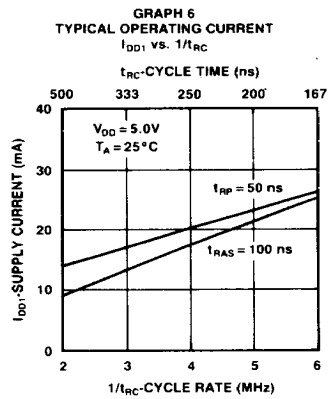
GRAPH 4
TYPICAL OPERATING CURRENT
I_{DD1} vs. V_{DD}



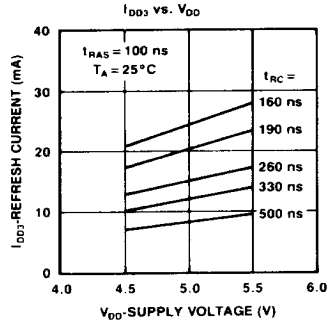
GRAPH 5
TYPICAL OPERATING CURRENT
I_{DD1} vs. T_A



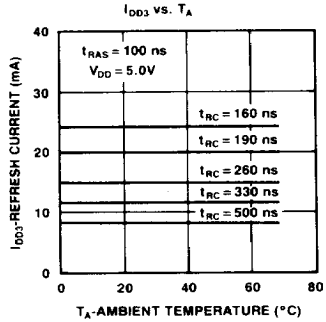
GRAPH 6
TYPICAL OPERATING CURRENT
I_{DD1} vs. $1/t_{RC}$



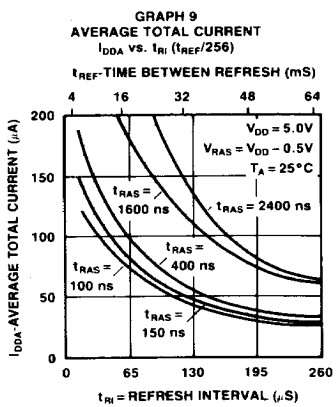
GRAPH 7
TYPICAL REFRESH CURRENT
I_{DD3} vs. V_{DD}



GRAPH 8
TYPICAL REFRESH CURRENT
I_{DD3} vs. T_A



GRAPH 9
AVERAGE TOTAL CURRENT
I_{DDA} vs. t_{RI} ($t_{REF}/256$)



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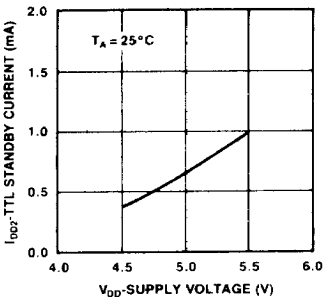
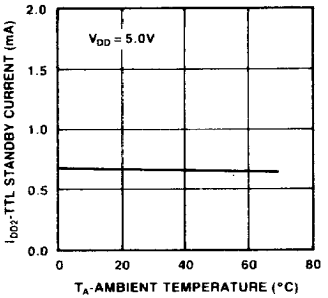
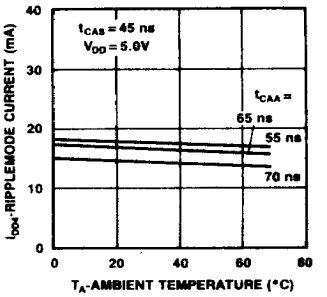
GRAPH 10
TYPICAL TTL STANDBY CURRENT
I_{DD2} vs. V_{DD}



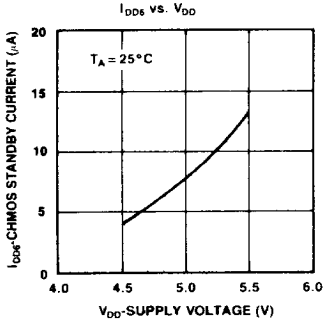
GRAPH 11
TYPICAL TTL STANDBY CURRENT
I_{DD2} vs. T_A



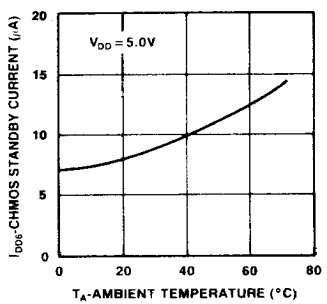
GRAPH 12
TYPICAL RIPPLEMODE CURRENT
I_{DD4} vs. T_A



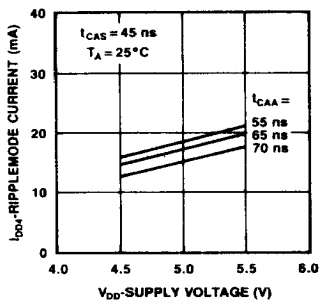
GRAPH 13
TYPICAL CHMOS STANDBY CURRENT
I_{DD6} vs. V_{DD}



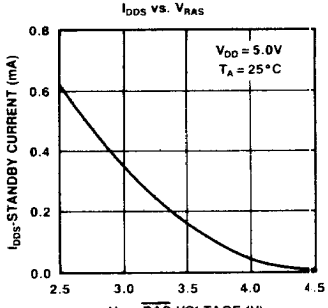
GRAPH 14
TYPICAL CHMOS STANDBY CURRENT
I_{DD6} vs. T_A



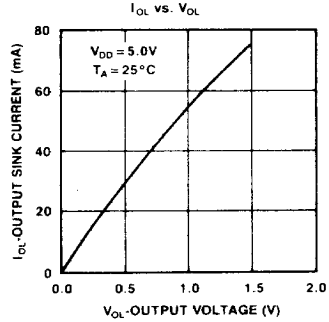
GRAPH 15
TYPICAL RIPPLEMODE CURRENT
I_{DD4} vs. V_{DD}



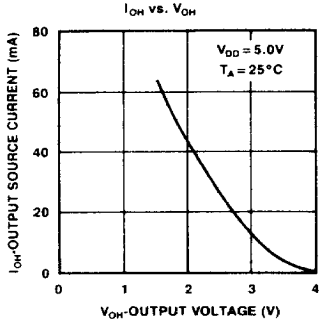
GRAPH 16
AVERAGE STANDBY CURRENT
RELATIVE TO $\overline{RAS}$ VOLTAGE
I_{DDS} vs. V_{RAS}



GRAPH 17
TYPICAL OUTPUT SINK CURRENT
I_{OL} vs. V_{OL}



GRAPH 18
TYPICAL OUTPUT SOURCE CURRENT
I_{OH} vs. V_{OH}



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FUNCTIONAL DESCRIPTION

The 51C64HL is a CHMOS dynamic RAM optimized for high data bandwidth and low power applications. The functionality is similar to a traditional dynamic RAM. The 51C64HL reads and writes data by multiplexing a 16 bit address into an 8 bit row and an 8 bit column address. The row address is latched in by the Row Address Strobe ($\overline{RAS}$). The column address, however, flows through the internal address buffer and is latched by the Column Address Strobe ($\overline{CAS}$). Because access time is primarily dependent upon a valid column address, the delay time between $\overline{RAS}$ and $\overline{CAS}$ can be long without affecting the access time.

Memory Cycle

The memory cycle is initiated by bringing $\overline{RAS}$ low. Any memory cycle once initiated must not be ended or aborted prior to fulfilling the minimum t_{RAS} timing specification. This ensures proper device operation and data integrity. Additionally, a new cycle cannot be initiated until the minimum precharge time, t_{RP} and t_{CP}, has elapsed.

Read Cycle

A read cycle is performed by maintaining the Write Enable ($\overline{WE}$) signal high during the $\overline{RAS}$/$\overline{CAS}$ operation. The column address must be held for a minimum time specified by t_{AR}. Data out becomes valid only when t_{RAC}, t_{CAA}, and t_{CAC} are all satisfied. Consequently, the access time is dependent upon the timing relationship among t_{RAC}, t_{CAA} and t_{CAC}. For example, the access time is limited by t_{CAA} when t_{RAC} and t_{CAC} are both satisfied.

Write Cycle

A write cycle is performed by taking $\overline{WE}$ and $\overline{CAS}$ low during a $\overline{RAS}$ operation. The column address is latched in by $\overline{CAS}$. The write cycle can be $\overline{WE}$ controlled or $\overline{CAS}$ controlled depending upon the later of $\overline{WE}$ or $\overline{CAS}$ low transition. Consequently, the input data must be valid at or before the falling edge of $\overline{WE}$ or $\overline{CAS}$, whichever occurs last. In a $\overline{CAS}$ controlled write cycle (the leading edge of $\overline{WE}$ occurs prior to or coincident with the $\overline{CAS}$ low transition) the output (D_{OUT}) pin will be in the high impedance state at the beginning of the write function. Terminating the write action with $\overline{CAS}$ will maintain the output in the high impedance state; terminating with $\overline{WE}$ allows the output to go active.

Refresh Cycle

To retain data, a refresh operation is performed by clocking each of the 256 row addresses (A_0 through A_7) with $\overline{RAS}$ at least every 4 milliseconds. Any Read, Write, Read-Modify-Write, or $\overline{RAS}$-Only cycle will perform refresh.

Extended Refresh Cycle

The 51C64HL extends the refresh cycle period to 64 milliseconds for $\overline{RAS}$-Only refresh cycles. This feature reduces the total current consumption to a maximum of 80 micro Amperes, and typically 15 micro Amperes, for data retention ($\overline{RAS}$-Only refresh operation for the 51C64HL-12). The low standby current can significantly extend battery life in battery back-up applications. Current consumption is calculated from the following equation:

$$I = \frac{(t_{RC}\, I_{ACTIVE}) + (t_{RI} - t_{RC})(I_{STANDBY})}{t_{RI}}$$

where t_{RC} = refresh cycle time,
and t_{RI} = refresh interval time or $t_{REF}/256$

Before entering or leaving an extended refresh period, the entire array must be refreshed at the normal interval of four milliseconds. This can be accomplished by either a burst or distributed refresh.

Ripplemode™ Operation

Ripplemode operation permits all 256 columns within a selected row of the device to be randomly accessed at a high data rate. Maintaining $\overline{RAS}$ low while successive $\overline{CAS}$ cycles are performed, retains the row address internally, eliminating the need to reapply it. The column address buffer acts as a transparent or flow through latch while $\overline{CAS}$ is high. Access begins from the valid column address rather than from $\overline{CAS}$, eliminating t_{ASC} and t_T from the critical timing path. $\overline{CAS}$ latches the addresses into the column address buffer and acts as an output enable.

During this operation read, write, read-modiy-write, or read-write-read cycles are possible at random or sequential addresses within a row. Following the entry cycle into Ripplemode operation, access time is t_{CAA} or t_{CAP} dependent. If the column address is valid prior to or coincident with the rising edge of $\overline{CAS}$, then the access time is determined by the rising edge of $\overline{CAS}$ specified by t_{CAP} as shown in Figure 1. If the column address is valid after the rising edge of $\overline{CAS}$, then the access time is determined by the valid column address specified by t_{CAA}. For both cases, the falling edge of $\overline{CAS}$ latches the address and enables the output.

Ripplemode operation provides a sustained data rate over 15 MHz for applications that require high data rate such as bit mapped graphics or high speed signal processing. The following equation can be used to calculate the data rate:

$$\text{Data Rate} = \frac{256}{t_{RC} + 255t_{PC}}$$

Data Out Operation

The 51C64HL Data Output (D_{OUT}), which has three-state capability, is controlled by $\overline{CAS}$. During $\overline{CAS}$ high

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state ($\overline{CAS}$ at V_{IH}), the output is in the high impedance state. Table 1 summarizes the D_{OUT} state for various types of cycles.

Power On

An initial pause of 100 μs is required after the application of the V_{DD} supply, followed by a minimum of eight initialization cycles (any combination of cycles containing a $\overline{RAS}$ clock such as $\overline{RAS}$-Only refresh). Eight initialization cycles are required after extended periods of bias without clocks (greater than 64 ms).

The V_{DD} current (I_{DD}) requirement of the 51C64HL during power on is dependent upon the input levels of $\overline{RAS}$ and $\overline{CAS}$. If $\overline{RAS}$ = V_{SS} during power on, the device would go into an active cycle and I_{DD} would exhibit large current transients. It is recommended that $\overline{RAS}$ and $\overline{CAS}$ track with V_{DD} or be held at a valid V_{IH} during power on.

Soft Error Rate

Soft errors are random, non-recurring changes in memory logic states caused by the impact of an ionizing particle, such as an alpha particle. For example, a logic "0" may change to a logic "1." The average soft error rate (SER) of the 51C64HL is less than 10 FITs. This is determined by accelerated testing using an alpha particle source and is subsequently confirmed by system testing. The SER is a function of the operating voltage, cycle time, package, and the alpha particle source. Intel measures the SER at V_{DD} = 4.75V, and t_{cycle} = 1μs. A thorium source of 1.6×10^5 α/cm^2/hr. is used because it best matches the package energy spectra.

References

For further details see Application Note (A.P.) #171, *Low Power with CHMOS DRAMS,* and A.P. #172, *CHMOS DRAMS in Graphics Applications.*

Table 1. Intel 51C64HL Data Output Operation for Various Types of Cycles

Type of Cycle	Data Out State
Read Cycle	Data from Addressed Memory Cell
$\overline{CAS}$ Controlled Write Cycle (Early Write)	High Impedance
$\overline{WE}$ Controlled Write Cycle (Late Write)	Active, Not Valid
Read-Modify-Write Cycle	Data from Addressed Memory Cell
Read-Write-Read Cycle ($\overline{CAS}$ Controlled)	Data from Addressed Memory Cell
Read-Write-Read Cycle ($\overline{WE}$ Controlled)	Data from Addr. Memory Cell and Active, Not Valid
$\overline{RAS}$-Only Refresh Cycle	High Impedance
$\overline{CAS}$-Only Cycle	High Impedance

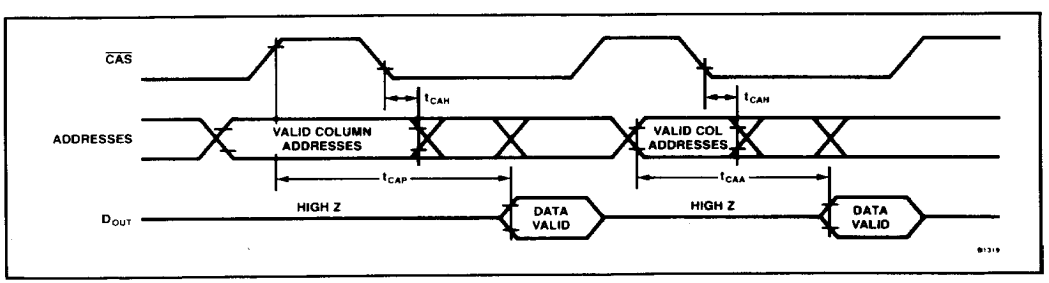

Figure 1. Ripplemode™ Access Time Determination

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